



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**PCN# 20251111003.1**  
**Qualification of additional BOM materials for selected devices**  
**Change Notification / Sample Request**

**Date:** November 12, 2025

**To:** MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

Change Management Team  
SC Business Services

**20251111003.1**  
**Change Notification / Sample Request**  
**Attachments**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
UCC28730DR	NULL
UCC28910DR	UCC28910DR
UCC28881DR	UCC28881DR
UCC28881D	UCC28881D
UCC28911DR	UCC28911DR

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20251111003.1			<b>PCN Date:</b>	November 12, 2025												
<b>Title:</b>	Qualification of additional BOM materials for selected devices																
<b>Customer Contact:</b>	Change Management team		<b>Dept:</b>	Quality Services													
<b>Proposed 1<sup>st</sup> Ship Date:</b>	February 10, 2026		<b>Sample Requests accepted until:</b>	January 11, 2026*													
<b>*Sample requests received after January 11, 2026 will not be supported.</b>																	
<b>Change Type:</b>																	
<input type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material												
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process												
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Fab Site												
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Material												
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process												
<b>PCN Details</b>																	
<b>Description of Change:</b>																	
This PCN is to inform of the qualification of an additional BOM materials for the list of devices in the product affected sections below.																	
<table border="1"> <thead> <tr> <th></th> <th>Current</th> <th>Additional</th> </tr> </thead> <tbody> <tr> <td>Wire diam/type</td> <td>0.96mil Au</td> <td>0.8mil Cu</td> </tr> <tr> <td>Mount compound</td> <td>EN-4088Z (4042500)</td> <td>QMI 505MT (4147858)</td> </tr> <tr> <td>Mold Compound</td> <td>EME-G720A (4212090)</td> <td>CEL-8240HFGK (4221499)</td> </tr> </tbody> </table>							Current	Additional	Wire diam/type	0.96mil Au	0.8mil Cu	Mount compound	EN-4088Z (4042500)	QMI 505MT (4147858)	Mold Compound	EME-G720A (4212090)	CEL-8240HFGK (4221499)
	Current	Additional															
Wire diam/type	0.96mil Au	0.8mil Cu															
Mount compound	EN-4088Z (4042500)	QMI 505MT (4147858)															
Mold Compound	EME-G720A (4212090)	CEL-8240HFGK (4221499)															
Qualification results are shown below																	
<b>Reason for Change:</b>																	
Continuity of supply																	
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>																	
None																	
<b>Impact on Environmental Ratings</b>																	
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.																	
<b>RoHS</b>		<b>REACH</b>		<b>Green Status</b>													
<input checked="" type="checkbox"/> No Change		<input checked="" type="checkbox"/> No Change		<input checked="" type="checkbox"/> No Change													
<b>IEC 62474</b>																	
<input checked="" type="checkbox"/> No Change																	
<b>Changes to product identification resulting from this PCN:</b>																	
<b>Die Rev:</b>																	
Current <b>New</b>																	
Die Rev [2P] <b>Die Rev [2P]</b>																	
A, B		<b>B, C</b>															
<b>Product Affected:</b>																	
UCC28910DG4	UCC28881DR	UCC28730DR	UCC28881DRG4														
UCC28910DR	UCC28911DR	UCC28881D	UCC28911D														
UCC28911DRG4	UCC28910D	UCC28730D															

## Qualification Report

Approve Date 19-December-2023

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: UCC28730DR	QBS Reference: UCC256604DDBR	QBS Reference: TPSI2140QDWQRQ1	QBS Reference: UCC28730QDRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	3/231/0	3/231/0
UHA	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	3/231/0
UHA	A3	Unbiased HAST	130C/85%RH	96 Hours	1/77/0	3/231/0	-	-
TC	A4	Temperature Cycle	-55C/150C	1000 Cycles	-	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	3/231/0	-	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	3/231/0	3/231/0	3/135/0	1/45/0
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	3/231/0	3/231/0
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	-	3/228/0
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	1/15/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	3/30/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	1/30/0	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/90/0	3/90/0

QBS: Qual By Similarity

Qual Device UCC28730DR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2308-018

# Qualification Report

Approve Date 05-August-2024

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: UCC28911D	QBS Reference: UCC256601DDBR	QBS Reference: TPS21400PWDBQ1	QBS Reference: UCC287800QRB1	QBS Reference: UCC256601DDBR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	3/231/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	3/231/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	-	-	-
TC	A4	Temperature Cycle	-55C/150C	1000 Cycles	-	-	3/231/0	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	-	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/231/0	3/135/0	1/45/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	3/231/0	3/231/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	3/2400/1 <sup>1</sup>	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	-	3/228/0	-
SD	C3	PB Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	1/15/0	-
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	1/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	3/30/0	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	-	-	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	-	1/3/0	1/3/0	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	1/3/0	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/3/0	1/6/0	1/6/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	1/30/0	-	-	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/90/0	3/90/0	-

QBS: Qual By Similarity

Qual Device UCC28911D is qualified at MSL2 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2401-110

[1]-One unit failed post 48 hrs ELFR. Failure analysis indicated that this unit most likely failed due to mishandling related EOS. Contact TI Quality group for full 8D report

### Product Attributes

Attributes	Qual Device: <u>UCC28730QDRQ1</u>	QBS Process, Product Reference: <u>TPSI2140QDWQRQ1</u>	QBS Process, Product Reference: <u>UCC28730QDRQ1</u>
Automotive Grade Level	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125
Product Function	Power Management	Power Management	Power Management
Wafer Fab Supplier	MH8, MH8	MH8, MH8	MH8, MH8
Assembly Site	MLA	TAI	MLA
Package Group	SOIC	SOIC	SOIC
Package Designator	D	DWQ	D
Pin Count	7	11	7

- QBS: Qual By Similarity
- Qual Device UCC28730QDRQ1 is qualified at MSL2 260C

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: <u>UCC28730QDRQ1</u>	QBS Process, Product Reference: <u>TPSI2140QDWQRQ1</u>	QBS Process, Product Reference: <u>UCC28730QDRQ1</u>
Test Group A - Accelerated Environment Stress Tests										
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL2 260C	-	3/0/0	-	3/0/0
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL3 260C	-	-	3/0/0	-
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	3/231/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	121C/15psig	96 Hours	-	3/231/0	3/231/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	-	-
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-55C/150C	1000 Cycles	-	3/231/0	-
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	-	3/231/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	-	1/5/0	3/15/0
TC-SAM	A4	-	3	3	Post TC SAM	<50% delamination	-	-	3/36/0	3/36/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	3/231/0	3/135/0	1/45/0
Test Group B - Accelerated Lifetime Simulation Tests										



Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: <u>UCC28730QDRQ1</u>	QBS Process, Product Reference: <u>TPSI2140QDWQRQ1</u>	QBS Process, Product Reference: <u>UCC28730QDRQ1</u>
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	3/231/0	3/231/0
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/1 <sup>1</sup>
Test Group C - Package Assembly Integrity Tests										
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	-
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	1/15/0	1/15/0
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	1/15/0	1/15/0	1/15/0
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	3/30/0	3/30/0	3/30/0
Test Group D - Die Fabrication Reliability Tests										
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDb	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: <u>UCC28730QDRQ1</u>	QBS Process, Product Reference: <u>TPSI2140QDWQRQ1</u>	QBS Process, Product Reference: <u>UCC28730QDRQ1</u>
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests										
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	-	1/3/0	1/3/0
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	1/3/0	1/3/0	1/3/0
LU	E4	AEC Q100-004	1	6	Latch-Up	Per AEC Q100-004	-	-	1/6/0	1/6/0
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	3/90/0	3/90/0	3/90/0
Additional Tests										

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

**Ambient Operating Temperature by Automotive Grade Level:**

- Grade 0 (or E): -40C to +150C
- Grade 1 (or Q): -40C to +125C
- Grade 2 (or T): -40C to +105C
- Grade 3 (or I) : -40C to +85C

**E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):**

- Room/Hot/Cold : HTOL, ED
- Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
- Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2303-028

[1]-One unit failed post 48 hrs ELFR. Failure analysis indicated that this unit most likely failed due to mishandling related EOS. Contact TI Quality group for full 8D report.

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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